

Preliminary Agenda 22 January 2008

**PRELIMINARY MEETING AGENDA –
CE-2.2 SUBCOMMITTEE ON CONNECTORS AND SOCKETS
(WAS SUBCOMMITTEES CE-2.2, 2.3, 2.4 AND 2.9)
31 March 2008 - 1 April 2008 (April Fools Day) in LOUISVILLE, KY**

1. Approval of the 24 25 September 2007 Minutes

2. SPECIFICATIONS BY PROJECT NUMBERS

"If any SP listed below receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting. It is the responsibility of the member to submit comments in writing prior to the meeting".

A. SP-4965, EIA-540B0AE, Detail Land Grid Array (Contech Research is sponsor)

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

B. SP-4970, EIA-540DAAA-A, Detail, DIP

At EDEC for approval.

C. SP-4971, EIA-700A0AB, 68-pin Memory Card Connector

At EDEC for approval.

D. SP-4973: EIA-540B0AB: Low Pin Count BGA

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

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E. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

A second letter (mccwil269) was sent to Cecelia Yates (EIA Staff) EDEC ballot on 14 August 2006.

F. PN-5123, EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

Sent the standard, background data sheet and cover memo (mccwil325) to EIA for letter ballot on 15 October 2007 on behalf of Tom Peel.

Ballot issued 19 October 2007 with a ballot expiration date of 19 November 2007.

3. SPECIFICATIONS AWAITING PROJECT NUMBERS

4. NEW BUSINESS

Prepared by:

Carl Fritz, Facilitator, CE-2.9